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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In Re Application of:

5 Jin-Yuan Lee et al.

Serial No.: 10/055,499

10 Filed: January 22, 2002

For: INTEGRATED CHIP PACKAGE

STRUCTURE USING ORGANIC

SUBSTRATE AND METHOD OF

15 MANUFACTURING THE SAME

Examiner: THAI, LUAN C

Art Unit: 2891

Docket No.: MEGP0012USA

RESPONSE TO FINAL OFFICE ACTION

20 COMMISSIONER FOR PATENTS

P.O. Box 1450

Alexandria, Virginia 22313-1450

25 Dear Sir:

The Final Office Action mailed Aug. 9, 2006 has been carefully considered. In response thereto, please enter the following amendments and consider the following remarks. A continued examination is politely requested.

30